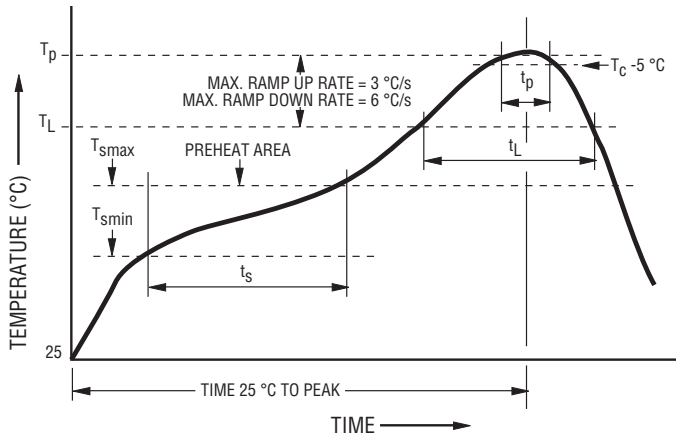


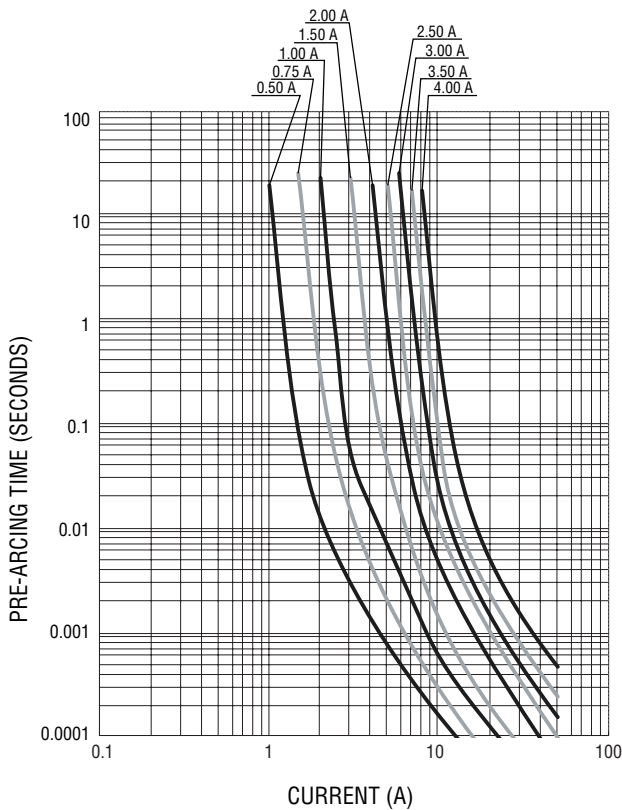
**Solder Reflow Recommendations**



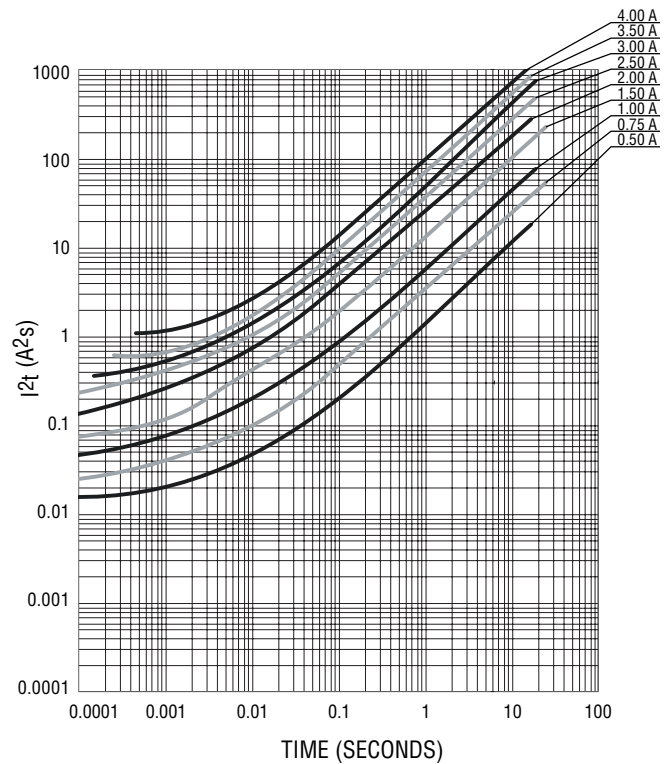
Profile Feature	Pb-Free Assembly
Preheat / Soak: Temperature Min. ( $T_{smin}$ ) Temperature Max. ( $T_{smax}$ ) Time ( $t_s$ ) from ( $T_{smin}$ to $T_{smax}$ )	150 °C 200 °C 60~120 seconds
Ramp Up Rate ( $T_L$ to $T_p$ )	3 °C / second max.
Liquidous Temperature ( $T_L$ ) Time ( $t_L$ ) maintained above $T_L$	217 °C 60~150 seconds
Peak Package Body Temperature ( $T_p$ )	260 °C
Time ( $t_p$ )* within 5 °C of the specified classification temperature ( $T_c$ )	30 seconds*
Ramp Down Rate ( $T_p$ to $T_L$ )	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.

\* Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

**Average Pre-Arcing Time vs. Current Curves**



**Average  $I^2t$  vs.  $t$  Curves**



Specifications are subject to change without notice.

Users should verify actual device performance in their specific applications.

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# SF-0603HlxxxF Series Tape and Reel Packaging Specifications

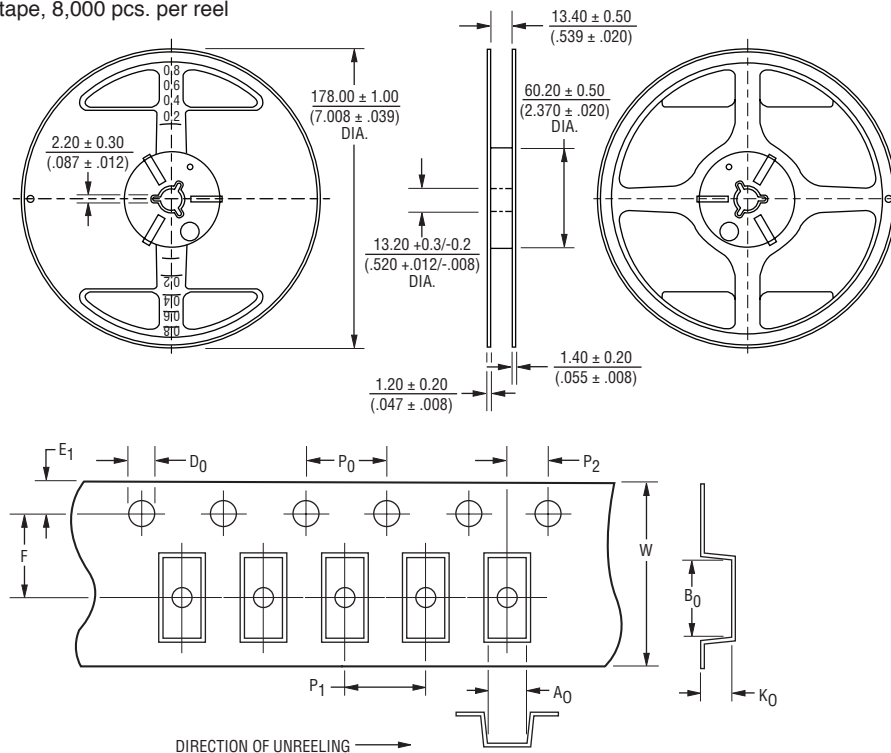


## SF-0603HlxxxF Series per EIA 481-2

### Tape Dimensions

W	$\frac{8.10 \pm 0.20}{(.319 \pm .008)}$
P <sub>0</sub>	$\frac{4.0 \pm 0.10}{(.157 \pm .004)}$
P <sub>1</sub>	$\frac{4.0 \pm 0.10}{(.157 \pm .004)}$
P <sub>2</sub>	$\frac{2.0 \pm 0.05}{(.079 \pm .002)}$
A <sub>0</sub>	$\frac{1.00 \pm 0.10}{(.039 \pm .004)}$
B <sub>0</sub>	$\frac{1.80 \pm 0.10}{(.071 \pm .004)}$
F	$\frac{3.50 \pm 0.05}{(.138 \pm .002)}$
E <sub>1</sub>	$\frac{1.75 \pm 0.10}{(.069 \pm .004)}$
D <sub>0</sub>	$\frac{1.55 \pm 0.05}{(.061 \pm .002)}$

PACKAGING: Paper tape, 8,000 pcs. per reel



DIMENSIONS:  $\frac{\text{MM}}{\text{(INCHES)}}$

REV. A 06/18

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